



HT-50 Y3 感光防焊油墨技术资料

HT-50 Y3 Photoimageable solder mask data sheet

一、性能介绍 Features:

易操作使用，高度解像，优良的附着力、耐热性及良好的耐电金、化金性能。

Easy operation, high resolution, good adhesion, heat resistance and good performance for electric gold, immersion gold.

二、技术资讯 Specification:

项目名称 Product name 项目 Items	HT-50 Y3
颜色 Color	黄色 Yellow
粘度 (主剂) Viscosity(main agent)	25℃, 粘度计/Brookfield Viscometer DV2T
	350±20dPa.s
混合比例 Mixing ratio	主剂: 硬化剂=75:25 Main agent: Hardener=75:25
混合后使用期限 Pot life after mixing	24 小时 (25℃以下暗处保存) 24hours(Store in dark place below 25℃)
保存期限 Shelf life	制造后 6 个月 6 months after production
附着力 Adhesion	100/100
铅笔硬度) Hardness	6H
耐溶剂性 Solvent resistance	PGM-AC, 室温下浸泡 30min 后, 以 3M 胶带做拉力测试, 无油墨脱落 PGM-Ac 30 min immerse at room temperature, no peeling off after tape test.
耐酸性 Acid resistance	10vol%H ₂ SO ₄ (aq), 室温下浸泡 30min 后, 以 3M 胶带做拉力测试, 无油墨脱落 10vol%H ₂ SO ₄ 30 min immerse at room temperature, no peeling off after tape test.
耐碱性 Alkaline resistance	10wt%NaOH(aq), 室温下浸泡 30min 后, 以 3M 胶带做拉力测试, 无油墨脱落 10 wt% NaOH 30 min immerse at room temperature, no peeling off after tape test.
耐焊锡 Solder resistance	288℃×10sec×3times
绝缘电阻 Insulation resistance	≥1.2×10 ¹¹ Ω
包装 Potting	1kg/套, 5kg/套 1kg/set, 5kg/set



三、操作程序 Process recommendations:

产品名称 Product name 项目 Items	HT-50 Y3	注意事项 Notes
调油 Mixing	添加适量专用稀释剂搅拌 5-10min, 静置 15min 以上再使用 Add the appropriate special diluent and stir 5-10min, hold 15min or more before using	稀释剂添加量可根据粘度需求进行添加 Diluent amount can be added according to the viscosity requirement
前处理 Pretreat	酸洗→磨刷→喷刷→高压水洗→水洗→烘干 金刚砂浓度: 18-22% 酸洗 H ₂ SO ₄ 浓度: 3-5% Acid washing→Scrubbing→Spray brush→High pressure water washing, →Rinsing→Drying Emery concentration: 18-22% H ₂ SO ₄ concentration: 3-5%	磨痕测试: 12-18mm 水破测试: ≥30s 喷痕测试: 同板面不同位置喷嘴堵塞≤5个 The grinding mark test: 12 to 18 mm The water break test: ≥ 30 s Spray mark test: with different location of the nozzle clogging ≤5
丝印/辊涂 Screen printing Roller coating	丝印网目: 36-43T 刮刀: 75度 辊涂 Silk screen mesh: 36-43T Squeegee: 75degree Roller coating	丝印完成后静置 15min 以上再进行预烤 Recommend to hold 10 minutes before prebaking
预烤 Pre curing	双面烘干: 75°C×35-45min Double-sided: 75°C×35-45min 单面烘干: Single-sided: 第一面: 75°C×18-20min, Side1: 75°C×18-20min, 第二面: 75°C×25-30min Side2: 75°C×25-30min	预烤或曝光后静置 15min 以上, 预烤到显影静置时间不可超过 24hr. Hold above 15min after pre curing and exposure, The hold time from pre curing to developing should not exceed 24hr.
曝光 Exposure	LDI 曝光机, 250-350mj/cm ² , 21 级曝光尺: 9-11 格 LDI exposure machine, 250-350 mj/cm ² , Stouffer 21 steps : 9-11 Steps.	
显影 Developing	Na ₂ CO ₃ 浓度: 0.8-1.2% Na ₂ CO ₃ concentration: 0.8-1.2% 温度: 28-32°C Temperature: 28-32°C 喷淋压力: 1.5-2.5kg/cm ² Spray pressure: 1.5-2.5kg/cm ² 时间: 55-70sec Time: 55-70sec PH 值: 9-11 PH value: 9-11	上喷淋比下喷淋压力大 0.5kg/cm ² 可以预防卡板, 显影点控制: 50-60% The above spray pressure is larger than the below spray pressure 0.5kg/cm ² can prevent the plug board , Developing point control: 50-60%
后烤 Final curing	65-170°C×16-18 仓, 时间 70-180 分钟。 65-170°C×16-18 oven, time: 70-180 minutes.	如塞孔板或厚铜板要求先低温分段烤后再高温固化 A plug hole or thick copper of PCB request five sections of baking at low temperature before high temperature curing

注明: 以上为建议参数, 现场使用时请根据自身工艺设备的实际情况进行调整。

Note: the above is the recommended parameters, on-site use, according to the actual situation of their own equipment to adjust.